



# High Density MRAM update

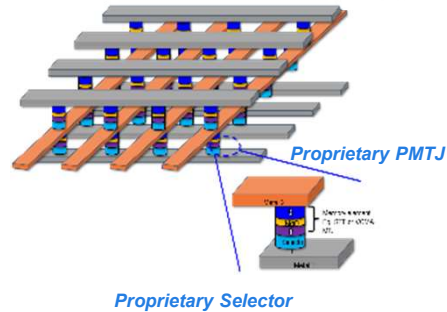
**Paul Chopelas, General Manager, Aerospace and Defense**

RHET Conference  
November 9<sup>th</sup>, 2023  
Allen, Texas

November 9, 2023

# Avalanche Company Overview

*Hi-Rel STT pMTJ MRAM since 2006*



**17+ years STT MRAM Experience**

**Domestic Technology**



**325  
Granted  
Patents &  
counting**

*Technology funded by DARPA in 2008*

*Most Next-Gen/STT MRAM Patents Stateside*

*Focused on Space and Hi-Rel Industrial*



**Hi-Rel Industrial Heritage**

Shipping volume to Industrial customers since 2019

**Hi-Rel Focused**

**Growing Ecosystem**

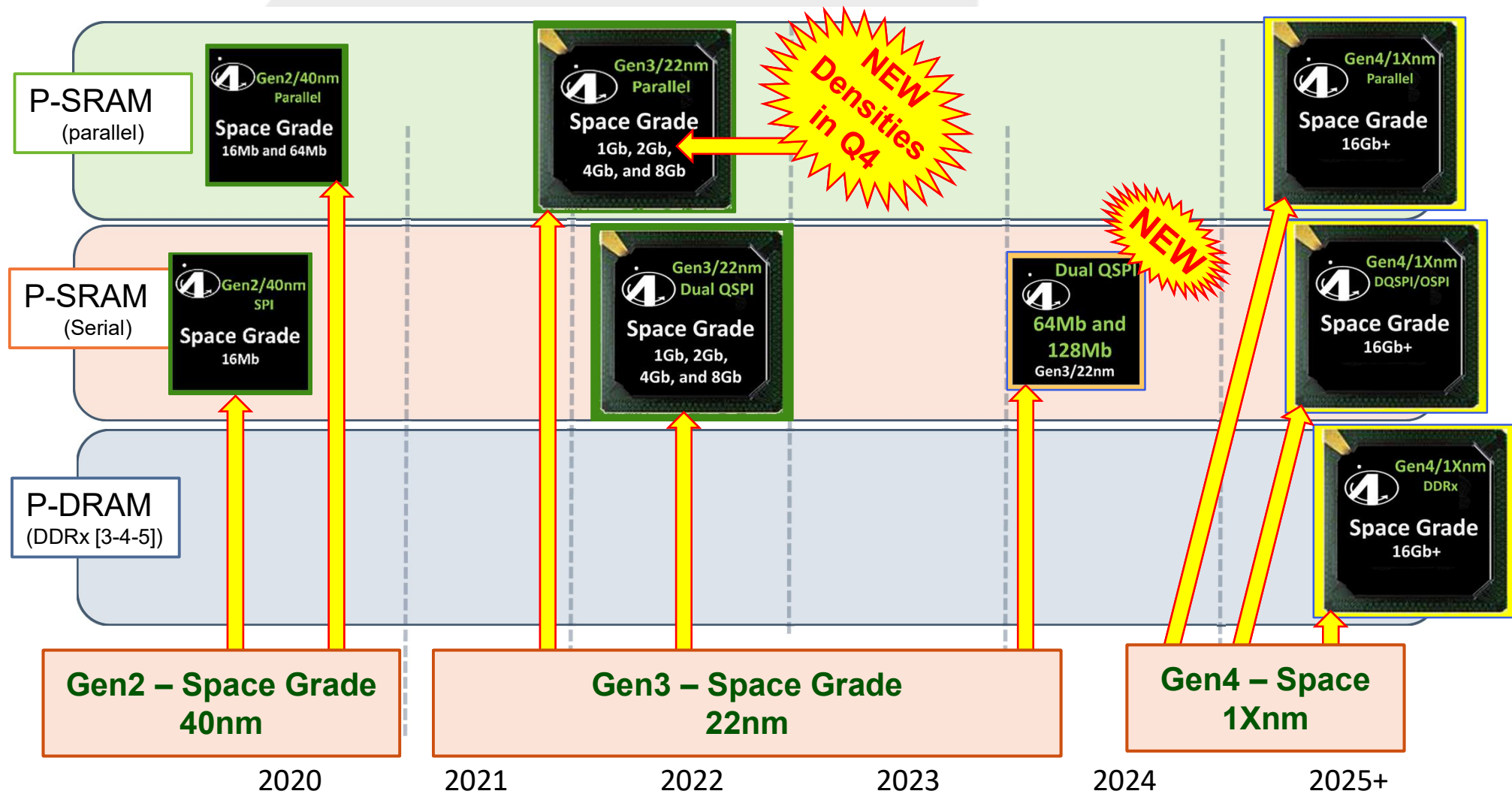


*Growing Fab and Partner Ecosystem...*

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# SILICON ROADMAP AND RADIATION

# Avalanche Current Products and Future Roadmap



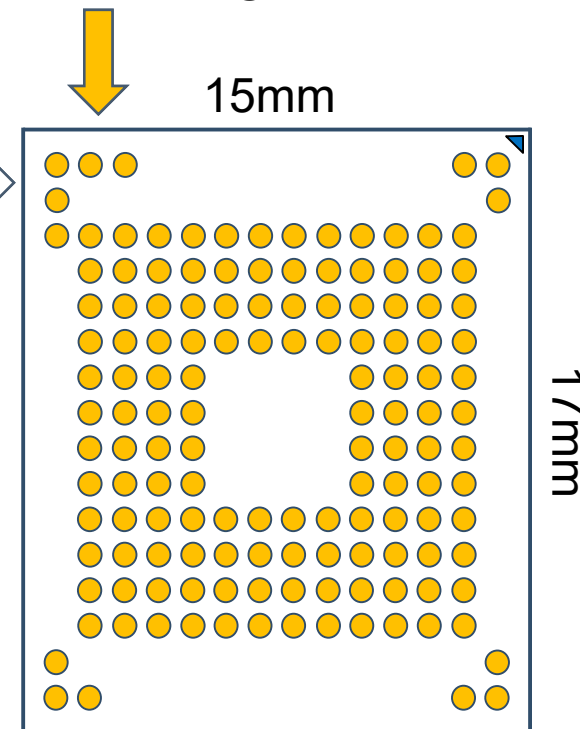


# Parallel – 1Gb to 8Gb with one layout



1Gb, 2Gb, 4Gb and 8Gb  
32Mbits/mm<sup>2</sup> @ 15mm x 17mm

Standard FBGA142

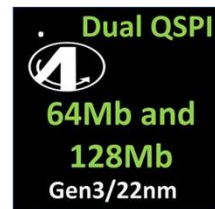


- Designed for the **Highest Reliability**:
  - Robust **On-chip ECC with multibit correction**
  - **Error-free** non-destructive **read w/ unlimited endurance**
  - **Error-free writes** with **10<sup>16</sup> endurance**
- **Ultra Low Power** (as low as 50mA per Gb active)
- No Shielding Required vs legacy Toggle MRAM
- **High Bandwidth Interface (711Mbps parallel/1.422Gbps streaming)**

# Serial (Dual QSPI) – 64Mb to 8Gb with one layout



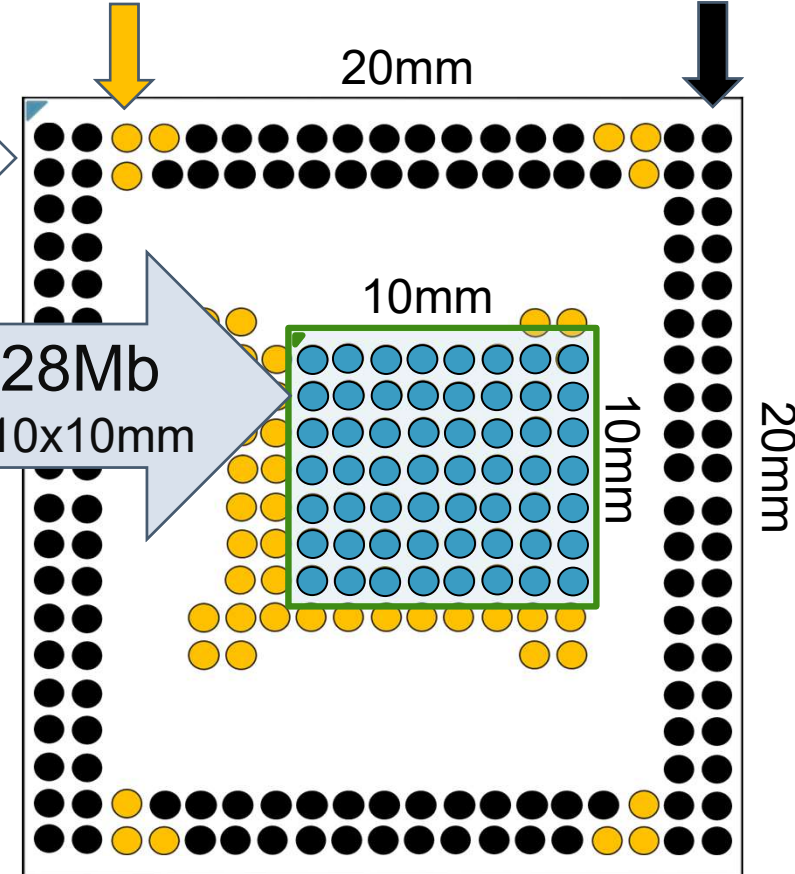
1Gb, 2Gb, 4Gb and 8Gb  
21Mbits/mm<sup>2</sup> @ 20x20mm



64Mb and 128Mb  
1.3Mbits/mm<sup>2</sup> @ 10x10mm

Standard FBGA96

Optional FBGA224



- Designed for the **Highest Reliability**:
  - Robust **On-chip ECC with multibit correction**
  - **Error-free non-destructive read w/ unlimited endurance**
  - **Error-free writes with 10<sup>16</sup> endurance**
- **Ultra Low Power** (as low as 50mA per Gb active)
- No Shielding Required vs legacy Toggle MRAM
- **Dual QSPI Interface 108Mhz/133MHz**

# Earth to Mars – Avalanche MRAM covers the spectrum

- Avalanche **MRAM technology & devices scalable** by radiation classification
- Avalanche productized **Space Grade as cost effective COTS+** solution
- Enabling partners with **wafers & knowhow** to support extended flows

Mission Use Case	Product Family	Qual Level & Screening	TID	SEE	Write Endurance	Retention	Packaging Options	ITAR
Terrestrial	Industrial Grade	JEDEC	<10KRad	<8 LET	10 <sup>14</sup>	20 Years	Plastic - RoHS	No
Avionics, Missile, LEO	Space Grade	JEDEC + 48hr burnin	<75KRad	~45 LET	10 <sup>16</sup>	10 Years	Plastic - Leaded & RoHS	No
GEO	QED	PEMS, QML, & Custom	100KRad	~75 LET	10 <sup>16</sup>	10 Years	Plastic - Leaded	Yes
GEO, Missile, Strategic	RadHard	QML, Custom	>300KRad	~75 LET	10 <sup>16</sup>	10 Years	Plastic, Hermetic, Die, MCM	Yes

# Gen3 SEE/TID **Production** Test Result Subset and Planning



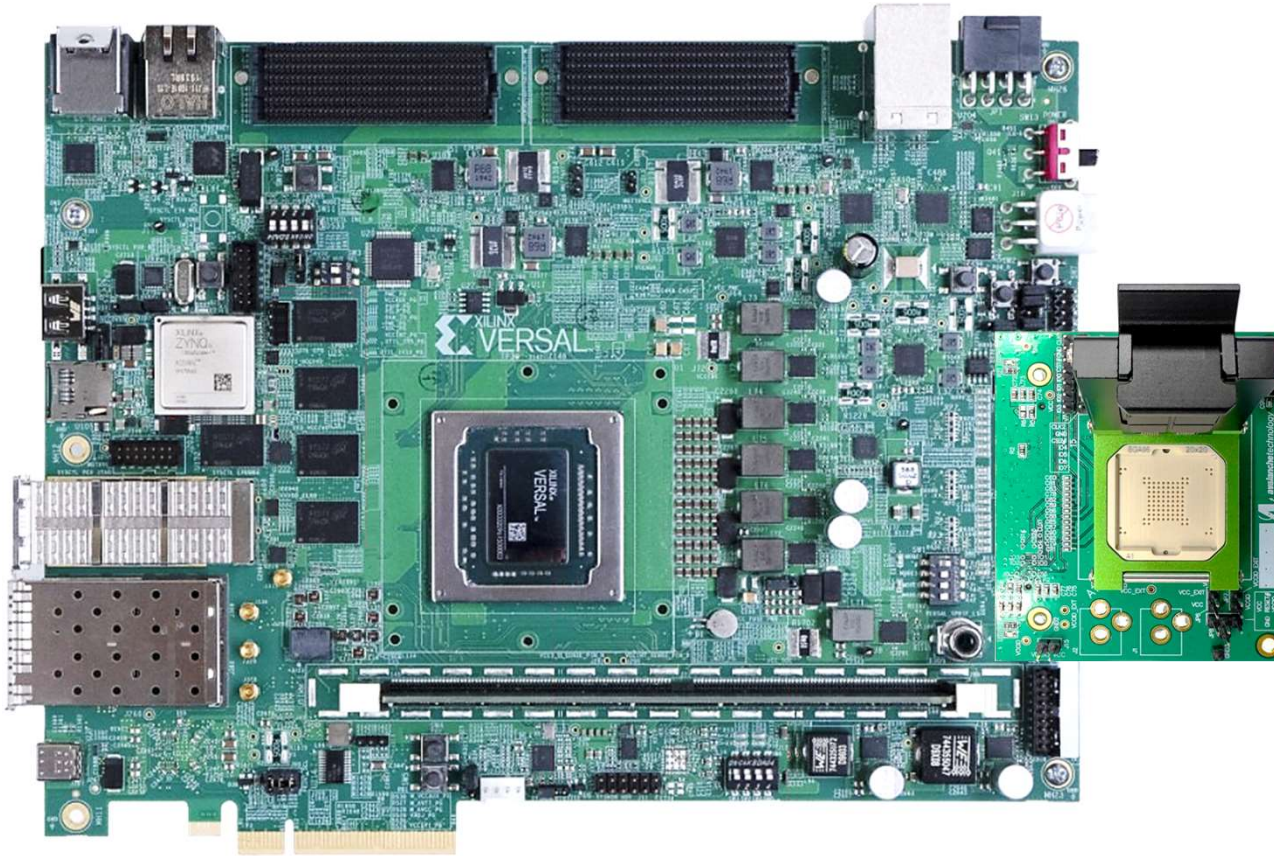
Device Rev	Test	Test Facility	Dates	Test Participants	Test Results
Test Chip	Heavy Ions	TAMU	Aug 2 '21	Avalanche Technology Apogee, CAES	No SEL @ Xe - 57.1MeV*cm <sup>2</sup> /mg @ 110°C
	Gamma	DMEA	Oct 7 '21	Microcross, DMEA Avalanche Technology	Negligible change in parametric data @ 175krads
<h2>In all the testing, by us or others, not a single data error has been observed!</h2>					
Early Production	Heavy Ions	TAMU	Jul 29 '22*	Avalanche Technology M&A	No SEL @ Ar - 8 & Cu - 18.9 @ >100°C HCE @ Ag - 44.9MeV*cm <sup>2</sup> /mg @ >110°C
	Gamma	DMEA	Sept 6 '22	Avalanche Technology DMEA	Negligible change in parametric data @ 75k, 100krads tested to 450krads
Production	Heavy Ions	TAMU	April 2, '23	Avalanche Technology Microcross	<b>No SEL @ Ho - LET 73.3 @ 25C or 60C</b> <b>HCE @ Ho - LET 73.3 @ &gt; 100C</b> <b>No SEFI or Write, Read, Compare Errors During Beam</b>
	Gamma	DMEA	June 8 '23	Avalanche Technology	Tested <b>1Gb MRAM</b> @ 50krad and 450krads Negligible change in parametric data @ 100krad and 450krads
	Gamma	DMEA	July 19 '23	Avalanche Technology	Tested <b>2Gb Dual-QSPI w/Chiplet</b> @ 50k, 100k & 150krads Negligible change in parametric data @ 50k & 100krads
	Heavy Ions	TAMU	Sept 15, '23 <b>Dec '23</b>	Customer/DoD Prime Avalanche Technology	Part 1: Tested <b>1Gb Parallel MRAM</b> and <b>2Gb Dual QSPI</b> Part 1 Test Results - Next Page <b>Performs additional tests after cycles of learning of part 1</b>



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# WE ENABLED THE PLATFORMS

# Enabled Booting and nvStorage for AMD/Xilinx Devices



Family	Petalinux Support				Fabric Only
	23.2	23.1	22.2	22.1	No O/S
Versal	Dec 15 <sup>TH</sup>	✓	✓	✓	✓
Ultrascale+	Dec 15 <sup>TH</sup>	✓	✓	✓	✓
Ultrascale	Dec 15 <sup>TH</sup>		Dec 1st		✓

<https://www.avalanche-technology.com/support/development-kits/>

## Gen 3 Space Grade Dual QSPI P-SRAM™ Kit for Xilinx



### Development Kit:

[Download the User Guide](#)  
[Download the Sample Code](#)  
[Xilinx/AMD Versal Boot Linux Drivers](#)

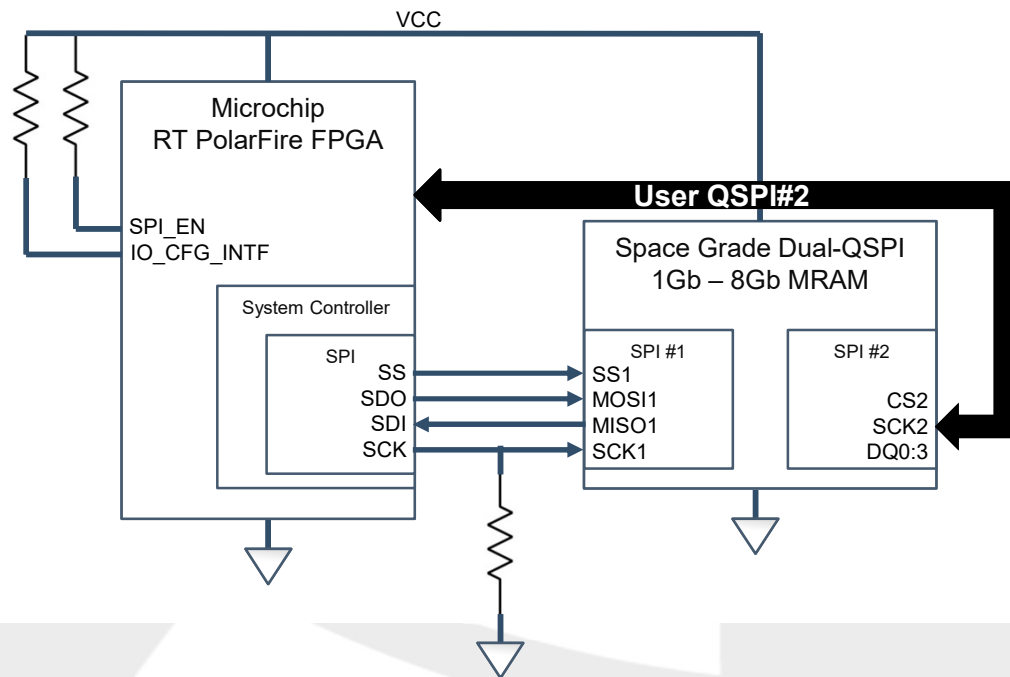
### Reference Design:

[Download the Schematic, Board Layout, Gerber, BOMs](#)

### Orderable Part Numbers:

Kit: AK30X208XILCCSOC  
 Socket: ABGA96-1-20x20

# Enabled auto-updating RT PolarFire's on-board Flash



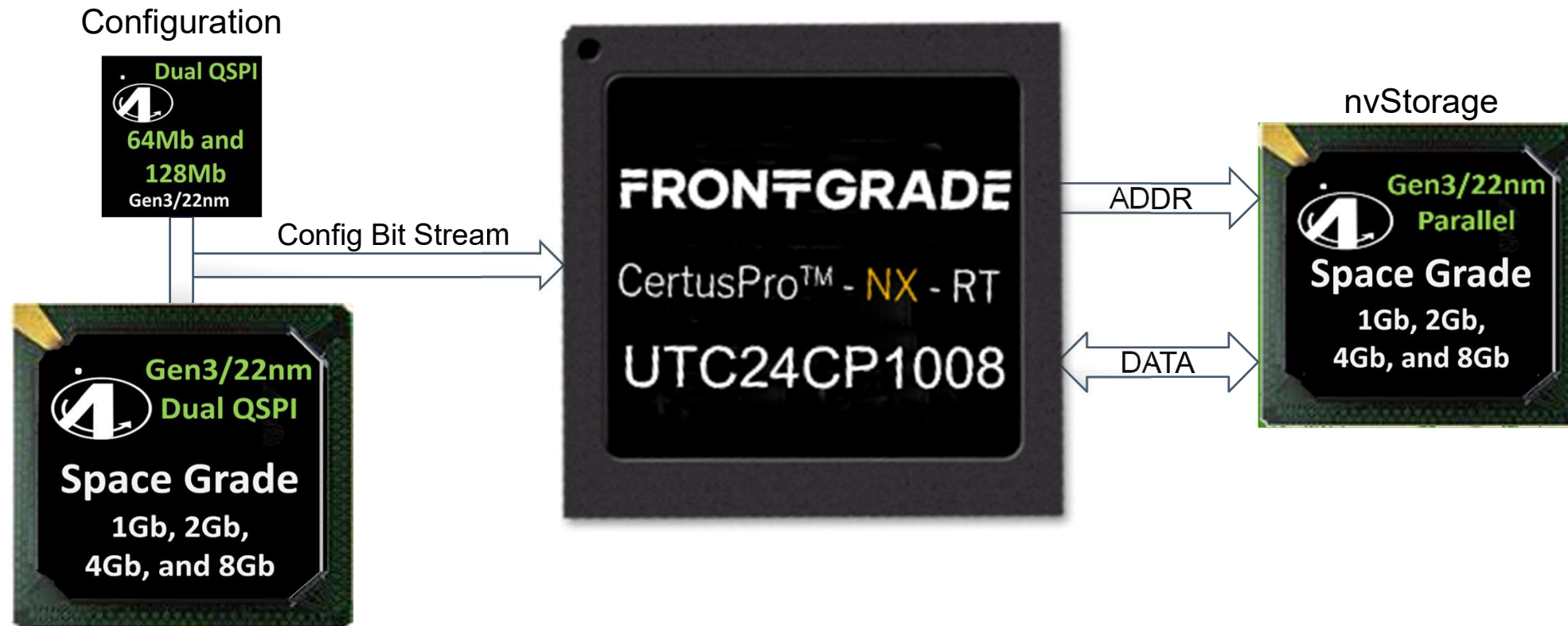
## SPI Directory

Addr	Sector 0
0	Image 0 Pointer
4	Update image Pointer
8	Image 1 Pointer
...	...
4*(N-1)	Image(N-1) Pointer

## SPI/MRAM Memory




# Enabling Booting/nvStorage for Frontgrade (Lattice) CertusPro FPGAs





## Enabling the driver for Storage Solutions in Space


- **Avalanche provides reference design with low level drivers**
- **Partnership with  EIDETICOM enabled plug and play NVMe stack**



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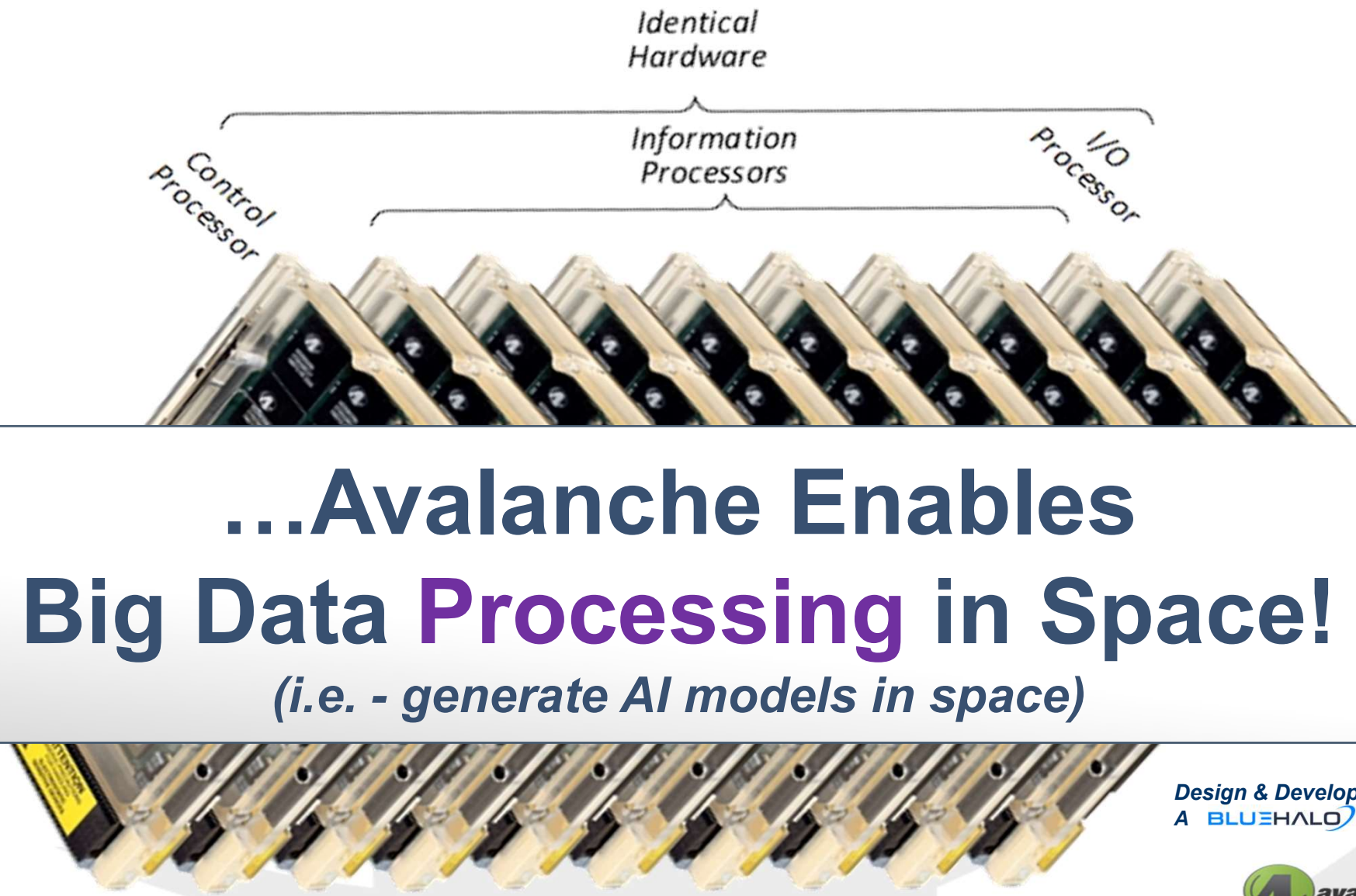
# PARTNERS DELIVERING FOR THE COMMUNITY

# BLUEHALO<sup>®</sup> enabled 8Gbyte MRAM Data Buffer

- 8GByte All MRAM Data Buffer
- Licensed NVMe stack from  EIDETICOM
- AI Memory: Xilinx KU060 FPGA supports data operations:
  - Compression, Cyber Security, Parameter Extraction, etc.
- High performance SSD
- $10^{16}$  Write Cycle Endurance
- Low power
- 3U VPX
- Affordable



# From In-Memory Computing, to the use of AI...

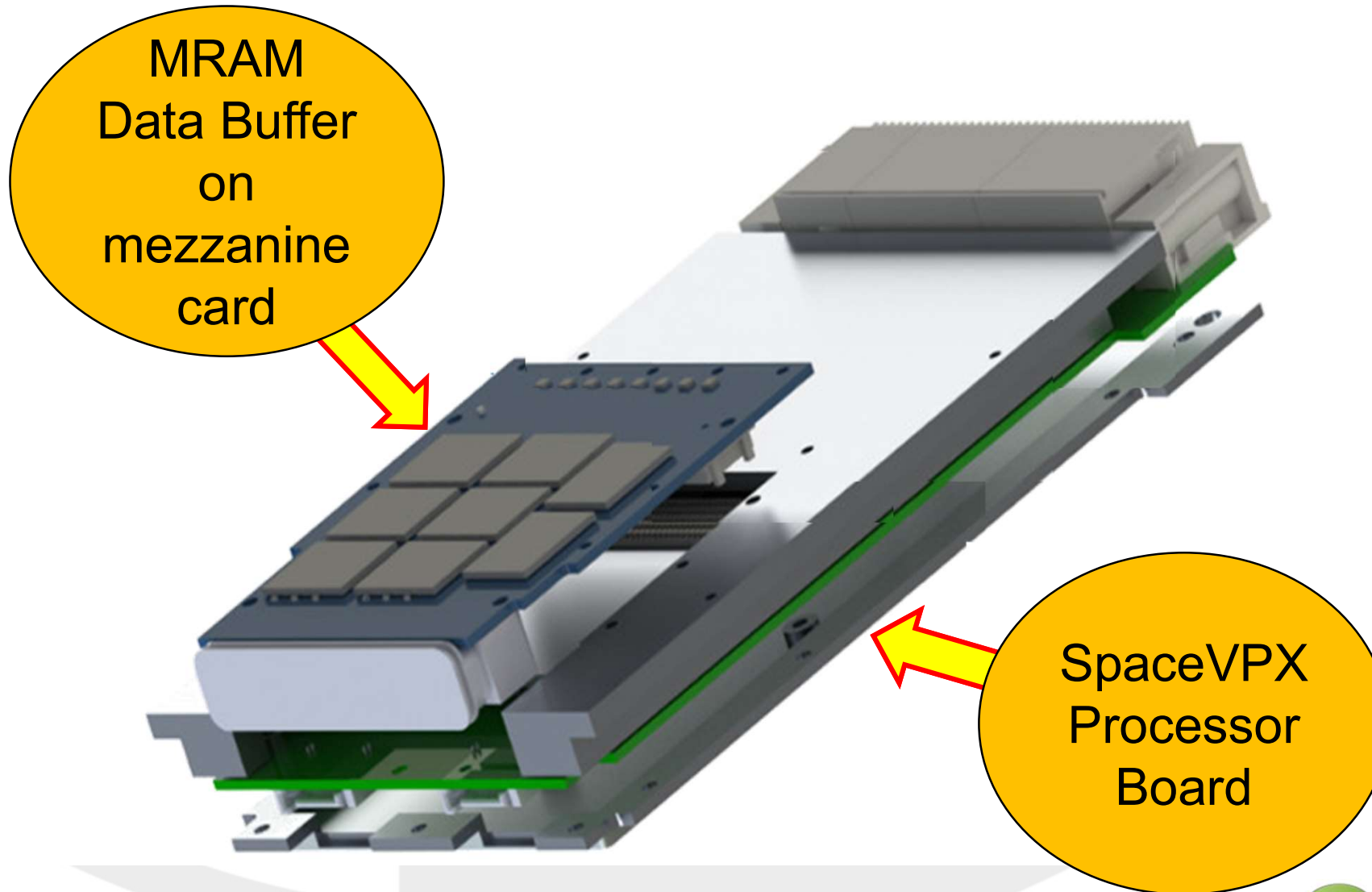






**TRUSTED**  
Semiconductor Solutions™

# enabled 8Gbyte Customizable Mezzanine Card

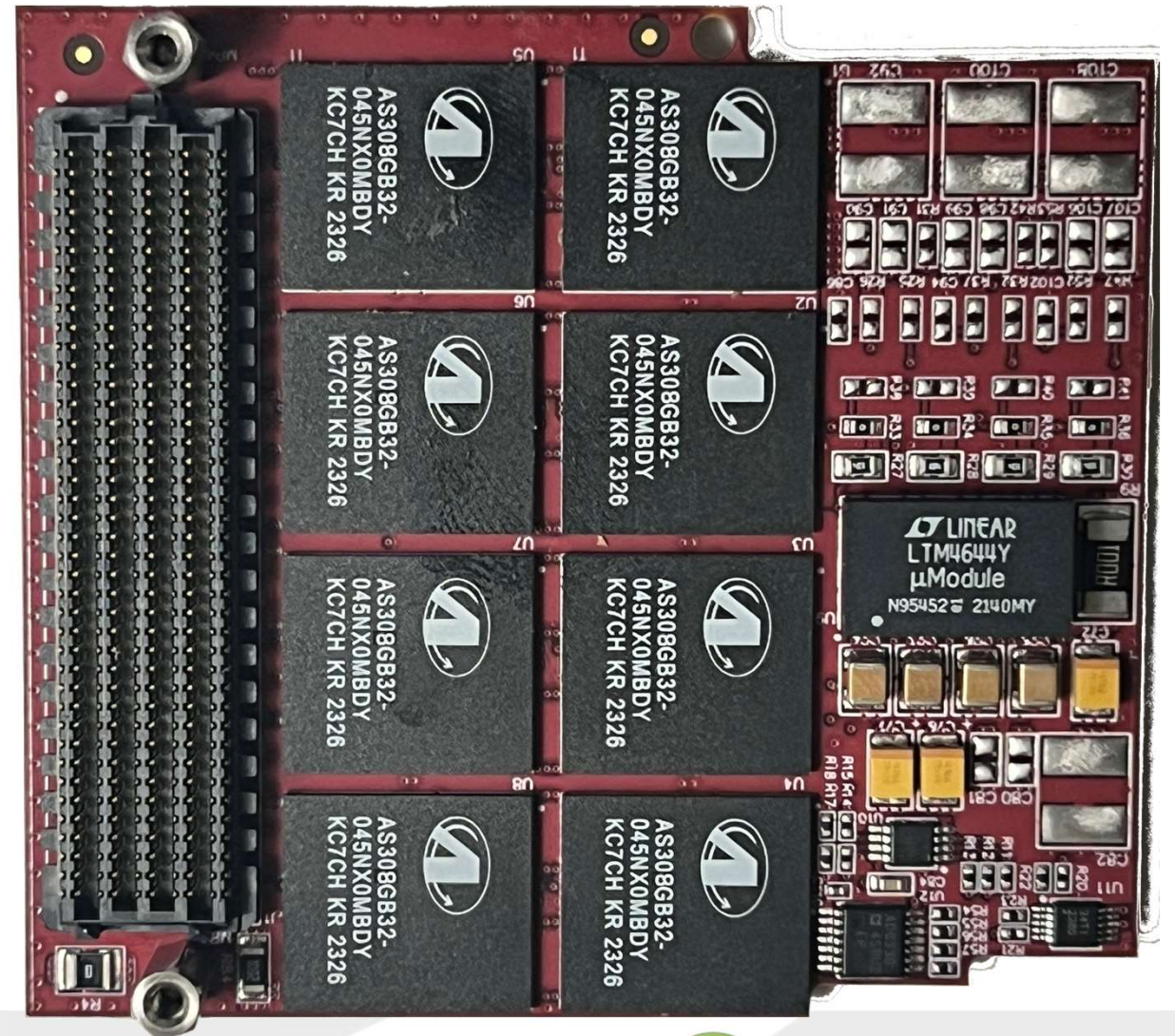




**TRUSTED**  
Semiconductor Solutions™

## enabled 8Gbyte Customizable Mezzanine Card

- Can use either 4Gbit or 8Gbit MRAM
- MRAM 8GByte Cache daughter card
  - Utilizes existing Xilinx Zynq board
- Hi-Rel 3U VPX board based on Agilex-5
  - Plan to make FMC compatible with MRAM Cache card
- Radiation Circumvented 3U VPX board
  - TSS developing PDDIC that detects, circumvents, and recovers from a radiation event
  - Will use the Agilex-5





# mercury enabled Hybrid (MRAM+NAND) SpaceDrives

## In Development

Quadrium 3U VPX Rad-Tolerant, Mirror Multi-Host, 350 GBytes NAND, 120 Mbit/s, 3.2 Gbit/s, Parallel, Octal SPI, SpaceDrive

Models: RH3350NM6S-000I01-01

- Rad-Tolerant non-volatile storage: 350 GBytes NAND plus 120 Mbit/s
- Triple-Redundancy for host Data and internal ECC bytes. Four, 8-bit, ECC correction
- Lesser screened, plastic RTG4 FPGA to enable cost sensitive NewSpace applications
- Rad-Tolerant, by design. All components except NAND.
- SpaceVPX compatible, 3U VPX form-factor, single 5V supply
- Lower cost, lower speed, implementation of Mercury's popular SpaceDrive product
- Multi-Host operation. Up to 6 hosts using Parallel, Octal SPI and SpaceFibre

The RMS350 is the first in a series of lower cost, radiation tolerant, NAND storage devices based on Mercury's popular SpaceDrive product. Using the latest generation of TLC NAND in SLC mode, the RH3350 is ideal for implementing high-reliability non-volatile storage in lower-cost applications requiring radiation tolerance. Space grade reliability is accomplished using Rad-Tolerant, by-design components (except NAND), 3 copies of host and Reed Solomon data. To better enable lower cost NewSpace applications, lesser screened versions of true RT-by-design components are utilized. A full screened **Premium** version is available by special order. The RMS350 replaces the cumbersome NAND flash command set and interface with flexible Parallel, SPI and SpaceFibre interfaces. Interfaces can be used together allowing multi-host operation. The full storage capacity is accessible by up to 6 hosts. Commands issued by interfaces are serviced based on bus ownership. Numerous status registers allow monitoring product health including PE counts, Retired Blocks, Spare Blocks, ECC errors and more. The RMS350 implements a deterministic, corruption-free shutdown process with an optional external capacitor to supply a

## mercury

## In Development

Quadrium Rad-Tolerant, Triple Redundancy Multi-host, 350 GBytes NAND, 120 Mbit/s, 3.2 Gbit/s, 120 pin Quad Plastic Pack

Models: RMS350NM6S-000I01-01

- Rad-Tolerant non-volatile storage: 350 GBytes NAND plus 120 Mbit/s
- Triple-Redundancy for Data and ECC bytes. Four, 8-bit, ECC correction
- Lesser screened RTG4 FPGA to better enable cost sensitive NewSpace applications
- Rad-Tolerant, by design. All components except NAND.
- Compact solder down form-factor, single 5V supply
- Lower cost implementation of Mercury's popular SpaceDrive product
- Multi-Host operation. Up to 6 hosts using Parallel, Octal SPI, SpaceFibre

The RMS350 is the first in a series of small form-factor radiation tolerant NAND storage devices based on Mercury's popular SpaceDrive (SSDR) product and packaged in a solder-down form-factor. Using the Micron B27C TLC NAND device in SLC mode, the RMS350 is ideal for implementing high-reliability non-volatile storage in lower-cost applications that require radiation tolerance. Space grade reliability is accomplished using Rad-Tolerant, by-design components (except NAND), and 3 copies of host and Reed Solomon data. To better enable lower cost NewSpace applications, lesser screened versions of true RT-by-design components are utilized. A full screened Premium version is available by special order. The RMS350 replaces the cumbersome NAND command set and interface with flexible Parallel, Octal SPI, and SpaceFibre interfaces. Interfaces can be used together allowing multi-host operation. The full storage capacity is accessible by up to 6 hosts. Commands issued by interfaces are serviced based by bus ownership and order received. Numerous status registers allow monitoring product health including PE counts, Retired Blocks, Spare Blocks, ECC errors and more. The RMS350 implements a deterministic, corruption-free shutdown process with an optional external capacitor to supply a

## mercury

## CONCEPT

Rad-Tolerant 6U VPX 100 Gbit/s Quad-Host SpaceDrive Host Capacity of 22 TB NAND plus 400 MBytes MRAM PCIe and mFAST interface options

Models:

RH622TNM6S-000I22-01 (22 TB EDU), RH622TNM6S-000I22-02 (22 TB Flight unit)

## mercury



- Radiation-tolerant storage for space and commercial applications with potential for radiation exposure
- 22 TB using 3D TLC NAND in SLC mode (60K PE cycles)
- 400 Mbytes of general purpose MRAM (100 MB/s)
- 6U VITA 78, 220mm (SpaceVPX compatible) form-factor
- Rad-Tolerant components
- Single 5V supply

The RH622T is the second product in the Mercury's **SpaceMax** series of radiation tolerant SpaceDrives. Designed to maximize both performance and capacity, the RH622T supports a raw data rate of 160 Gbps and a sustained host data throughput of 100 Gbits/s. This represents a 5.5X improvement in performance and a 4.8X increase in capacity compared to the Boron 4.5TB SpaceDrive. Like all members of the **SpaceMax** series, the RH622T utilizes the latest generation of 3D TLC NAND running in SLC mode. Host capacity remains constant across the entire life through use of very strong error correction and more than 16% of additional capacity dedicated to spare blocks. To keep power consumption low, the RH622T utilizes multiple low power PolarFire FPGAs operating in parallel. Each PolarFire manages 25% of the capacity using four 10-Gbps SERDES Lanes per PolarFire. A single host can control the entire capacity, or four hosts can each control 25% of the capacity independent from the other 75% of the capacity. Designed for fault tolerance with multiple failed NAND devices, the

- Radiation-tolerant design details:
  - NAND: Micron B27C die, PEM. TID >30 krad. Screened to EEE-INST-002
  - MRAM: Avalanche Gen3. 100 krad TID, SEE > LET 45 MeV.cm2/mg
  - PolarFire NAND Controller
    - TMR of critical logic. 1.2V I/Os for best SEL tolerance.
    - Total ionizing dose (TID) > 100 krad
    - Configuration upsets immunity to LET > 80 MeV.cm2/mg
    - Single-event latch-up (SEL) immunity to LET > 80 MeV.cm2/mg
    - Registers SEU rate < 10-12 errors/bit-day (GEO Solar Min)
    - SET upset rate < 10-8 errors/bit-day (GEO Solar Min)
  - All other devices: Radiation Tolerant, by design, to >100K rad
- VPX connectors:
  - Guide block key is adjustable and ships in the 0° position
  - Smith's KVFX Series: 500 mate/unmated cycles
  - TE connectivity MultiGig RT 2-R Series: 500 mate/unmated cycles
- Operating modes: Linear and Host Addressable
  - Linear Mode: Sequential data recording (Data recorder mode)
  - Host Addressable mode: operations on individual NAND blocks



# Enabling mercury's DeepSpace all MRAM 1TB SpaceDrive

## Early Concept

mercury

Magneto 6U **All-MRAM** SpaceDrive ( *DeepSpace Series* )  
100 Gbit/s Rad-Tolerant Quad-Host **1 TB Solid State Recorder**



Models: RH601TNAMS-000I10-01 (1 TByte EDU), RH601TNAMS-000I10-02 (1 TByte FLT)

- TID: > 100 krad (Si), SEE: > 70 LET
- Multiply redundant storage for high reliability space applications
- All space-grade MRAM, no NAND or DRAM. Virtually wear-out proof storage
- 6U SpaceVPX compatible form-factor
- Small/Adjustable block size and very high performance
- Single 5V supply



### Standard Features - continued

- All components RT-by-Design, 100 krad minimum
- Redundancy in both power and storage logic

Mercury's *DeepSpace* series of radiation-tolerant data recorders are designed for longer missions requiring higher reliability. The products utilize the highest quality RT-by-design-



# Summary...



## Architectural Simplicity

- **No wear leveling**
- No need for scrubbing, multiple copies
- **Soft errors corrected on the fly**



## Best SWaP Profile

- **Highest Density** (up to 8Gb)
- **Lowest Nominal Power** (50mA/Gb)
- No Shielding Required



## Footprint Scalability

- From 64Mb to 8Gb. Earth to Mars.
- JEDEC through QML Qual
- Common H/W for S/W defined systems



## Enabling Platforms for TTM

- **Hardware Reference Designs**
- Base level software drivers
- **Full software stacks through partnerships**

# Thank You!



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